

ABSTRACT**SYSTEM AND METHOD FOR LEAD FOOT ANGLE INSPECTION USING
MULTIVIEW STEREO VISION**

The present invention includes a system and method for three-dimensional imaging and analysis of electronic components. Specifically, it permits rapid and reliable inspection of the lead foot angle in integrated circuit packages. A first image capturing device, a second image capturing device and a third image capturing device are arranged in a "corner shape" or "L-shape." The first image capturing device forms the corner and obtains an image of the bottom of the component. The perspective viewing angle of the second image capturing device and the perspective viewing angle of the third image capturing device are orthogonal to each other to allow accurate three-dimensional reconstruction of the lead angles and detection of flaws or bends.

Figure 1 accompanies the abstract.